

## Ultra Small, Low Power & Modular Rugged Computer

## Ultra-SFF rugged embedded computer designed and manufactured by ECRIN Systems

Based on the latest generation of Intel processors and qualified according to the military equipment environmental standards (D0-160, MIL-STD-810 & MIL-STD-461), the nanoONYX is a low-power, rugged, and scalable computing solution for air, land and sea systems.

Being the most compact of a complete range of rugged computers, the nanoONYX is ideal for any demanding application requiring both high performance in a dense passively cooled system and the support of functions such as AI, graphics, and cybersecurity.

With its modular and robust design, the nanoONYX offers the embedded market a completely mil-qualified and customizable solution benefitting from a long-term support.

## The nanoONYX:

- supports a wide range of processor as the Intel® Atom™ E3950 processor, the Intel® Core™ i7-8665UE, or the Intel® Core™ i7-1185GRE through Mini-COM Express processor module, type 10
- features four expansion slots supporting AcroPack® mPCle-based Rugged I/O Modules and offering a large array of additional I/O as Ethernet, ARINC429, DAC, ADC, ...

Using the nanoONYX, system integrators benefit from a ruggedized, fully qualified and durable COTS solution with a high-quality technical support.

 Intel® Atom™ E3950 @ 1.6GHz, 12W, Quad-Core, 8GB DDR3L

**DESIGNED & PRODUCED** 

- Intel Core™ i7-1185GRE @ 1.8GHz, 15W, Quad Core, 16GBytes LPDDR4X
- Intel® Core™ i7-8665UE @ 1.7GHz, 15W, Quad-Core, 8GB DDR3L
- 1x DVI-D single link graphic output
- 2x GbE
- 2x RS-232, 2x RS-422 and 4x USB 2.0
- 4x AcroPack / mini PCle expansion slots for Avionics and Industrial I/O
- TPM 2.0
- 1x internal M.2 SSD slot
- Cableless, fanless, MIL-DTL-38999 connectors
- Qualified according DO-160, MIL-STD-461, MIL-STD-810
- Operating temperature:
- -40°C to +55°C without external air flow +71°C depending on processor version and
- Long Life Management with revision control
- ITAR free
- High flexibility to Modified COTS services
- Optional Holdup module, 200ms



System specifications		
Processor / Memory	Intel® Atom™ E3950 @ 1.6GHz, 12W, Quad-Core, 8GB DDR3L Intel Core™ i7-1185GRE @ 1.8GHz, 15W, Quad Core, 16GBytes LPDDR4X Intel® Core™ i7-8665UE @ 1.7GHz, 15W, Quad-Core, 8GB DDR3L	
TPM	TPM 2.0 Infineon Software TPM (Intel® Core™ i7-8665UE)	
Video	1x DVI-D single link output	
Ethernet	2x 10/100/1000Base-T Ethernet (i210 / i219)	
Audio	1x Line In, 1x Line Out	
USB	4x USB2.0	
Serial	2x RS232 (Tx, Rx, GND) 2x RS422 (Tx+, Tx-, Rx+, Rx-, GND)	
GPI0	2x GP Inputs (LVTTL) 2x GP Outputs (LVTTL)	
GPS	GPS antenna and 1 pps (via mini PCle function)	
Storage	1x M.2 (S42) SATA SSD internal slot	
Expansion slots	4x AcroPack / mini PCle slots Supporting Ethernet, ARINC429, MIL-STD-1553, RS232/424, DIO, ADC, DAC, CAN bus,	
Discrete I/O	On front panel: Power LED On MIL-DTL-38999 connector: Power button (ATX/AT CPLD mode), Reset button	
Hardware Monitoring	Internal voltages; CPU and carrier board temperatures	



Apollo Lake COMe Type 10



J1: +28VDC; 3 pts

J2: 2x GbE, DVI-D, 2x USB, RS 232/422, Antenna, 1x pps, PWR-ON & reset Btn; 55 pts

J3: AP #3 & #4 (30-pin), 2x USB, RS 232/422, Audio; 85 pts J4: AP #1 (50-pin), AP #2 (30-pin), 4x GPI0; 85 pts

Power supply	
Power Input	+28VDC (+12VDC up to +36VDC)
Power consumption	Up to 30W, 25W typic
Optional Holdup module	According to D0160, Section 16, Category A, 200ms (290ms @ 35W)

SWaP-C constraints	
Size (WxDxH)	205mm (L) x 140 mm (W) x 67.5 mm (H) including connectors With Holdup module: 205mm (L) x 140 mm (W) x 78,9 mm (H) including connectors
Weight	Without Holdup module and AcroPack : 1,9kg - With Holdup module and without AcroPack : 2,3kg
Cooling types	Conduction cooled system: convection & radiation by fins, conduction by cold plate or forced air flow
Connectors	MIL-DTL-38999 connectors Front panel customizable for specific applications

Environmental Qualification Tests					
Operating temperature	-40°C to +55°C without external air flow	Sand & Dust	Wind and fine dust particles; DO-160		
	+71°C depending on processor version and cTDP	Shock & vibration	40g@11ms; D0-160		
Storage temperature	-40°C / +85°C	EMI / RFI	According to DO-160 / MIL-STD-461		
Ingress protection rating	IP67	CE certification	EN 55032: 2015 / A1: 2019 Electromagnetic compatibility		
Altitude	Up to 116 mbar (50000ft); D0-160		of multimedia equipment - Emission requirements EN 55035: 2017: Electromagnetic compatibility of multimedia equipment - Immunity requirements		
Humidity	0%-95% @ 65°C and 0-85°C @ 38°C RH; D0-160				
Salt fog	50% salt spray @ 96h; D0-160		EN 62368-1:2014+AC:2015: Part 1: Safety requirement		

Software corner		
Operating system	Windows 10 32/64-bit, Linux 32/64-bit. For other requirements, contact ECRIN Systems	
Other specifications		
Regulatory compliance	European CE Mark, REACH, RoHS, WEEE, CoC	
Starter cable set	Breakout cable set mates with MIL-DTL-38999 connectors to break out standard CPUI/O and power signals to traditional PC style interfaces	
	for lab purposes	
Development kit	Starter kit based on same hardware building blocks for quick and easy integration and debugging	

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